

GrandTwin SuperServer SYS-212GT-HNF

2U 4-Node GrandTwin with up to 8 hot-swap E1.S NVMe drives per node and Front I/O



Key Applications

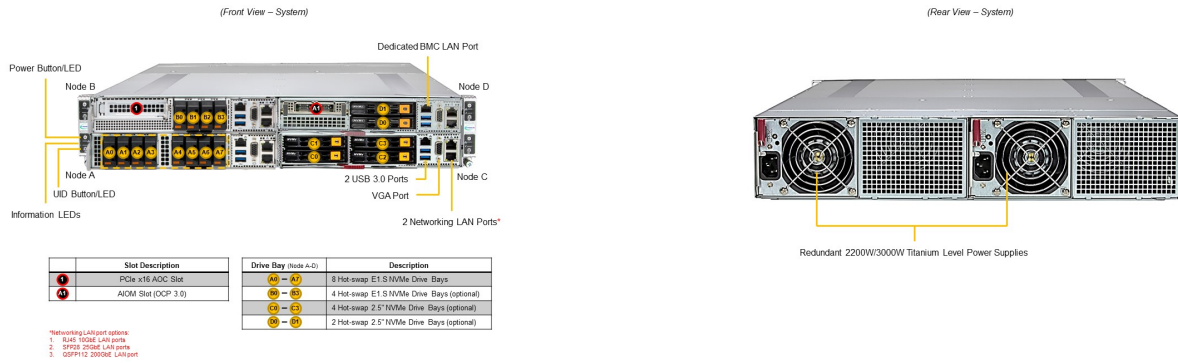
Enterprise Applications, Scale-Out Object Storage, Cloud Computing, Compact Server, Web/Hosting Application, Cloud Gaming, MEC (Multi-Access Edge Computing), Multi-Purpose CDN, Telco Edge Cloud, Mission Critical Web Applications, IoT Edge Computing / Gateway, Edge AI Inferencing,

Key Features

- Highly configurable 2U 4-Node front access nodes for cold aisle serviceability with up to 8x E1.S NVMe drives per node;
- 1 PCIe 5.0 x16 LP slot(offering with 4x E1.S drives), or 1 OCP3.0 slot (offering with 2x U.2 drives) for networking expansions;
- GrandTwin front IO module offers additional networking options (10G/25G/200G) with NCSI support;
- Single-Socket, Intel® Xeon® 6 6700 series processors with E-cores;
- 16 DIMM Slots supporting up to 1TB of memory; ECC RDIMMs up to DDR5-6400;
- Four **hot-pluggable** systems (nodes) in a 2U form factor. Each node supports the following;:



Form Factor	2U Rackmount Enclosure: 449 x 88 x 711.2mm (17.67" x 3.46" x 28") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache
System Memory	Slot Count: 16 DIMM slots/2 Channels Max Memory (2DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 8 bay(s) <ul style="list-style-type: none"> • 8 front hot-swap E1.S PCIe 5.0 x4 NVMe* drive bay(s) Option A: Total 4 bay(s) <ul style="list-style-type: none"> • 4 front hot-swap E1.S PCIe 5.0 x4 NVMe* drive bay(s) Option B: Total 4 bay(s) <ul style="list-style-type: none"> • 4 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) Option C: Total 2 bay(s) <ul style="list-style-type: none"> • 2 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) (*NVMe support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default)/2280; USB 2.0; VROC required for RAID)
Expansion Slots	PCI-Express (PCIe) Configuration: Default* <ul style="list-style-type: none"> • 1 PCIe 5.0 x16 LP slot(s) (*Requires additional parts, please see the optional parts list for details. For more details on PCIe slot configuration options, please refer to the system callout images above.) M.2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)
On-Board Devices	NVMe: NVMe; RAID 0/1/5/10 support(VROC HW key required) Chipset: System on Chip Network Connectivity: Via IO Module
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port(s) USB: 2 USB 3.0 port(s) Video: 1 VGA port(s)



System Cooling	Fans: 2x 16K RPM Heavy Duty 8cm Fan(s)
Power Supply	2x 3000W Redundant (1 + 1) Titanium (certification pending) Level (96%) power supplies
System BIOS	BIOS Type: AMI 64MB Flash ROM
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Weight: Gross Weight: 88 lbs (39.9 kg) Net Weight: 68 lbs (30.8 kg) Available Color: Silver
Operating Environment	RoHS Compliant Operating Temperature: 5°C ~ 40°C (41°F ~ 104°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X14SBT-G
Chassis	CSV-GT214E-R3K01TBP